



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <small>* : Required Field</small>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2020-09-17
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	giovanni giacopello	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T2535T-8T	7BVP*208SBM1	A	3068	2020-09-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	-	

Package Designator	Size	Nbr of instances	Shape	
SIP	10.00,9.10,4.50	3	Through hole	
Comment	TO 220 NI CLIP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.52	die - leadframe	272
Lead	6.04	soft solder	3179
Lead-Borate Glass	2.39	die	1260

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	6.04	Soft solder	3180
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	6.042	Soft solder	920195

Material Composition Declaration :						Mfr Item Name	7BVP*208SBM1					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	13.979	mg	supplier	die	Silicon(Si)	7440-21-3		10.925	mg	781529	5752
				supplier	metallisation	Gold(Au)	7440-57-5		0.056	mg	4006	29
				supplier	metallisation	Nicke(Ni)	7440-02-0		0.516	mg	36913	272
				supplier	passivation	Silicon oxide	7631-86-9		0.088	mg	6295	46
Leadframe	M-004 Copper and its alloys	1252.999	mg	JIG-R & California 65	glass	Lead-BorateGlass	65997-18-4	7c-I-Electrical and electronic	2.394	mg	171257	1260
				supplier	alloy & coating	Copper(Cu)	7440-50-8		1251.746	mg	999000	658814
				supplier	alloy & coating	Copper Posphorous(CuP)	12517-41-8		1.253	mg	1000	659
Soft solder	Solder	6.566	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	6.042	mg	920195	3180
				supplier	solder	Silver(Ag)	7440-22-4		0.164	mg	24977	86
				supplier	solder	Tin(Sn)	7440-31-5		0.327	mg	49802	172
				supplier	solder	Flux residue	proprietary		0.033	mg	5026	17
Encapsulation	M-011 Other inorganic materials	588.478	mg	supplier	mold compound	Silica vitreous	60676-86-0		436.650	mg	741999	229816
				supplier	mold compound	Phenol resin	9003-35-4		29.424	mg	50000	15486
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		64.733	mg	110001	34070
				supplier	mold compound	other	proprietary		52.963	mg	90000	27875
				supplier	mold compound	Carbon black	1333-86-4		4.708	mg	8000	2478
connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348
Clip		31.616	mg	supplier	alloy	Copper(Cu)	7440-50-8		31.616	mg	1000000	16640